



0.60mm (.024") Pitch DDR / DDR 2 SODIMM Connectors

FEATURES AND SPECIFICATIONS

[查询"48212-0200"供应商](#)

Molex's offers the complete range of SODIMM sockets solutions for the Notebook PC markets

The demand for faster performing notebook PC has provided a major challenge to notebook PC system designers. High speed and long battery life becomes a must for power user on the road. To deliver a product that is both fast and efficient in power management, one of the few key considerations is the power consumption of the memory module/socket.

The 200 circuits DDR/DDR2 SODIMM socket provides such a solution for notebook PC designers. Due to its' small form factor, it enables notebook PC designer to use smaller chassis. This allows for the development of smaller and lighter notebook PC. Though both the DDR (2.5 volt) and DDR2 (1.8 volt) version of the SODIMM socket are almost identical, the differentiating factor is the location of the voltage key. This prevents the wrong type of memory module from mating with the socket. DDR2 is the next-generation DDR memory technology. It is faster, higher bandwidth, lower power consumption and better thermal management.

Molex is an active member of JEDEC work group which defines standards for the memory industry. The DDR/DDR2 SODIMM Socket accepts modules that meet the JEDEC MO-224 outline. It comes in Lead Free plating and is RoHS compliant.

48212

Reverse Mount

48213

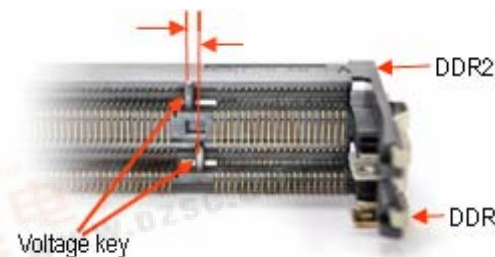
Standard Mount



Features

Benefits

- | | |
|---|---|
| • Low profile | • Provide 4.0mm & 5.2mm Height |
| • Standard & Reverse version | • Flexible of PCB layout design |
| • Plastic latches with metal support constrain movements of the plastic latches | • User will not over bend the latch when they released module |
| • High Temperature Thermoplastic housing | • Capable of lead free solder processing temperatures |
| • Tape & Reel packing | • For customer auto pick & place assembly process. |



SPECIFICATIONS

Reference Information

Packaging: Embossed Tape & Reel

UL File No.:

CSA File No.:

Mates With: JEDEC Standard Memory Modules

Designed In: mm

Electrical

Voltage: 50 AC

Current: 0.50A.

Contact Resistance: 30 milliohms max.

Dielectric Withstanding Voltage: 200V AC

Insulation Resistance: 100 Megohms min.

Mechanical

Contact retention force: 2.45N (0.55 lb)

Durability: 30 cycles

Physical

Housing: Liquid Crystal Polymer, Glass-filled)

Contact: Phosphor Bronze (CuSn)

Plating:

Contact Area — 0.13 μ m (5 μ "") Gold (Au)

Solder Tail Area — Gold (Au) Flash.

Underplating — Nickel (Ni)

PCB Thickness: 1.6mm

Operating Temperature: -40°C to 85°C



MARKETS AND APPLICATIONS[查询"48212-0200"供应商](#)

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DDR / DDR 2 SODIMM
Connectors**

**48212
Reverse Mount**

**48213
Standard Mount**

Notebook Industry

ORDERING INFORMATION

Description	Features		
	Lead-free Order No.	Mounted Height	Power Supply
0.60mm (.024") Pitch DDR SODIMM Socket, Right Angle, Reverse Mount, 200 Circuits	48212-0100	4.00mm (.157")	2.5V
	48212-0200	5.20mm (.205")	
0.60mm (.024") Pitch DDR2 SODIMM Socket, Right Angle, Reverse Mount, 200 Circuits	48212-1100	4.00mm (.157")	1.8V
	48212-1200	5.20mm (.205")	
0.60mm (.024") Pitch DDR SODIMM Socket, Right Angle, Standard Mount, 200 Circuits	48213-0100	4.00mm (.157")	2.5V
	48213-0200	5.20mm (.205")	
0.60mm (.024") Pitch DDR2 SODIMM Socket, Right Angle, Standard Mount, 200 Circuits	48213-1100	4.00mm (.157")	1.8V
	48213-1200	5.20mm (.205")	



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